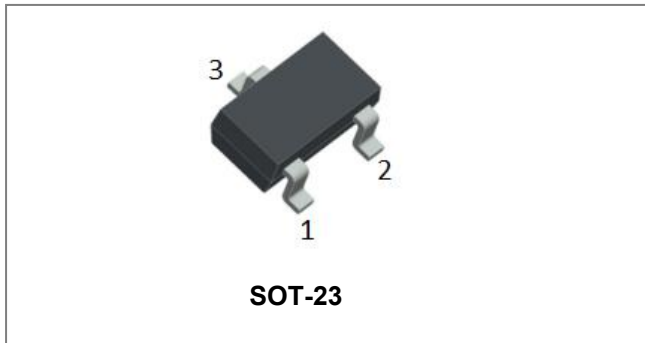


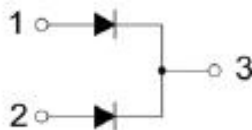
BAV70 SWITCHING DIODE



Features

- High Conductance
- Fast Switching
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose and Switching
- Plastic Material - UL Recognition Flammability Classification 94V-O
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Schematic & Pin Configuration



Mechanical Characteristics

- Case: SOT-23, Molded Plastic
- Terminals: Plated leads Solderable per MIL-STD-202, Method 208
- Mounting Position: Any
- Marking: A4

Maximum Ratings @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

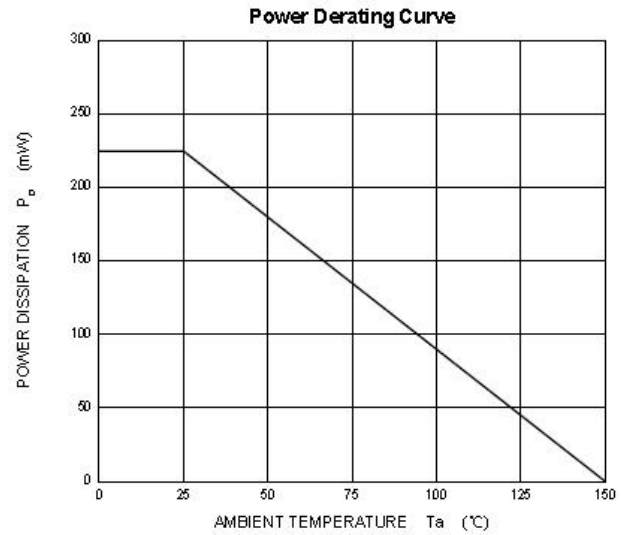
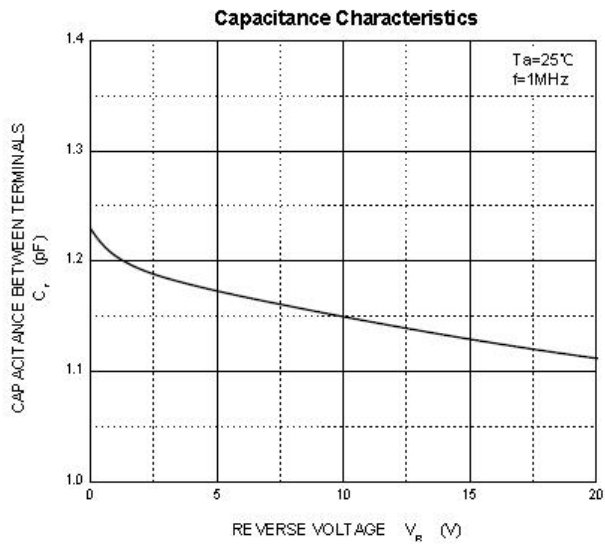
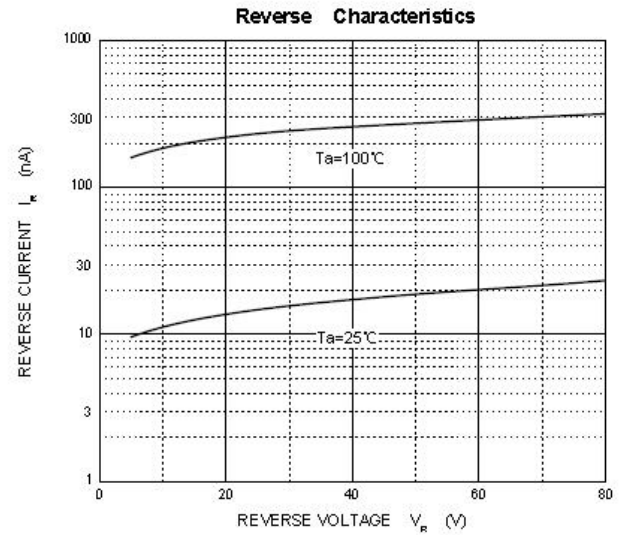
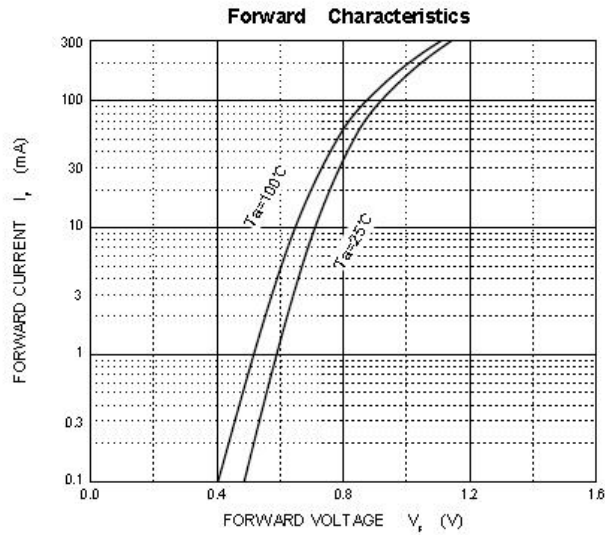
Characteristic	Symbol	Limits	Units
Reverse Voltage	V_R	70	V
Forward Current	I_F	200	mA
Non-Repetitive Peak Forward Surge Current @ $t=8.3\text{ms}$	I_{FSM}	2.0	A
Power Dissipation	P_D	225	mW
Typical Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	556	$^{\circ}\text{C/W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Max	Units	Test Condition
Reverse Breakdown Voltage*	V_{BR}	70	-	V	@ $I_F=100\mu\text{A}$
Forward Voltage*	V_F	-	0.715 0.855 1 1.25	V	@ $I_F=1\text{mA}$ @ $I_F=10\text{mA}$ @ $I_F=50\text{mA}$ @ $I_F=150\text{mA}$
Reverse Leakage Current*	I_R	-	2.5	μA	@ $V_R=70\text{V}$
Capacitance between terminals	C_T	-	1.5	pF	$V_R=0\text{V}, f=1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	-	6.0	ns	$I_F=I_R=10\text{mA}, I_{RR}=0.1 \times I_R, R_L=100\Omega$

* Pulse width < 300 μs , duty cycle < 2%
 Note: 1. Device mounted on fiberglass substrate 40x40x1.5mm

Ratings and Characteristics Curves

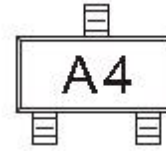


Ordering Information

Device	Package	Shipping
BAV70	SOT-23 (Pb-Free)	3000pcs / reel

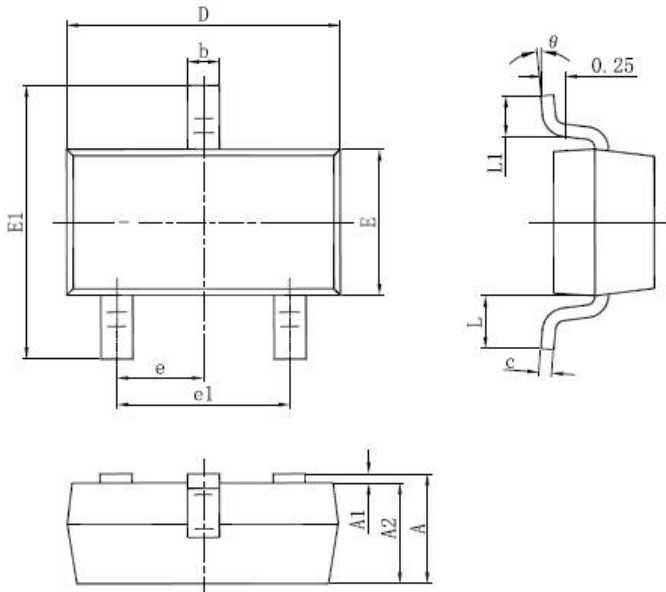
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



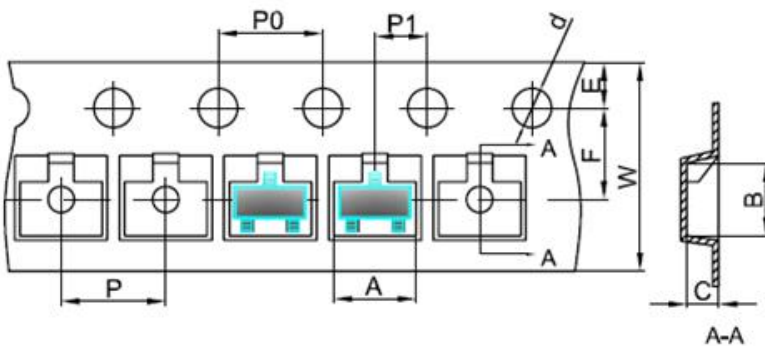
A4 = Marking Code

Mechanical Dimensions SOT-23



SYMBOL	Millimeters		Inches	
	MIN.	MAX.	MIN.	MAX.
A	0.890	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.076	0.170	0.003	0.007
D	2.650	3.050	0.104	0.120
E	1.190	1.400	0.047	0.055
E1	2.100	2.550	0.083	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.780	2.050	0.070	0.081
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Carrier Tape Specification SOT-23



SYMBOL	Millimeters	
	Min.	Max.
A	3.05	3.25
B	2.67	2.87
C	1.12	1.32
d	1.40	1.60
E	1.65	1.85
F	3.40	3.60
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
W	7.90	8.30

DISCLAIMER:

1- The information given herein, including the specifications and dimensions, is subject to change without prior notice to improve product characteristics. Before ordering, purchasers are advised to contact the SMC - Sangdest Microelectronics (Nanjing) Co., Ltd sales department for the latest version of the datasheet(s).

2- In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, medical equipment, and safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement.

3- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any damages that may result from an accident or any other cause during operation of the user's units according to the datasheet(s). SMC - Sangdest Microelectronics (Nanjing) Co., Ltd assumes no responsibility for any intellectual property claims or any other problems that may result from applications of information, products or circuits described in the datasheets.

4- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any failure in a semiconductor device or any secondary damage resulting from use at a value exceeding the absolute maximum rating.

5- No license is granted by the datasheet(s) under any patents or other rights of any third party or SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.

6- The datasheet(s) may not be reproduced or duplicated, in any form, in whole or part, without the expressed written permission of SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.

7- The products (technologies) described in the datasheet(s) are not to be provided to any party whose purpose in their application will hinder maintenance of international peace and safety nor are they to be applied to that purpose by their direct purchasers or any third party. When exporting these products (technologies), the necessary procedures are to be taken in accordance with related laws and regulations..